



6133 North River Road
Suite 500
Rosemont, IL 60018 Chicago

August 12nd, 2026

RE: PCN # ESU270-107- Bonding Wire Material Change Approval for SP1105S-01UTG

To our valued customer,

Littelfuse would like to notify you that we are going to change bonding wire material for SP1105S-01UTG TVS Diode Array (SPA® Diodes) product. There are no changes to fit, form, and function of finished product.

The affected product will be fully qualified in accordance with established performance and reliability criteria. Samples would be provided upon your request.

Form, fit, function changes: None

Part number changes: None

Effective date: Nov 12nd, 2026 or sooner

Replacement products: N/A

Last time buy: N/A

This PCN is for your information and acknowledgement. If you have any other questions or concerns, please contact your local sales team or product team below for further assistance.

We value your business and look forward to assisting you whenever possible.

Best Regards,

Sophia Hu
TVS Diode Array Assistant Product Manager
Semiconductor Business Unit, Wuxi, China
+86 510 85277701 - 7653
shu@littelfuse.com



6133 North River Road, Suite 500, Rosemont, IL 60018 Chicago

Product/Process Change Notice (PCN)

PCN# :

ESU270-107 Date: Aug 12nd 2026

Product Identification:

Bonding Wire Material Change Approval for
SP1105S-01UTG

Implementation Date for Change:

Nov 12nd, 2026 or sooner

Contact Information

Name : Sophia Hu

Title : Assistant Product Marketing Manager

Phone # : +86 13771377277

Fax# : N/A

E-mail : shu@littelfuse.com

Category of Change:

- ☐ Assembly Process
- ☐ Data Sheet
- ☐ Technology
- ☐ Discontinuance/Obsolescence
- ☐ Equipment
- ☐ Manufacturing Site
- ☒ Raw Material
- ☐ Testing
- ☐ Fabrication Process
- ☐ Other: _____

Description of Change:

To change bonding wire material for SP1105S-01UTG SPA™ TVS Diode Array product. There are no changes to fit, form, function of the finished product.

Important Dates:

- ☒ Qualification Samples Available: Upon request
- ☒ Final Qualification Data Available: Upon request
- ☐ Date of Final Product Shipment:

☐ Last Time Buy:

Method of Distinguishing Changed Product

- ☐ Product Mark,
- ☒ Date Code,
- ☒ Other, Littelfuse internal work order documentation

Demonstrated or Anticipated Impact on Form, Fit, Function or Reliability:

N/A

LF Qualification Plan/Results:

Yes

Customer Acknowledgement of Receipt: Littelfuse requests you acknowledge receipt of this PCN. In your acknowledgement, you can grant approval or request additional information. Littelfuse will assume the change is acceptable if no acknowledgement is received within 30 days of this notice. Lack of any additional response within 90 days of PCN issuance further constitutes acceptance of the change.



Prepared By : Roger Fan-Product Manager,
Ye Xin -Product Engineer, Sophia Hu-Assistant Product Manager
Date : 2026/08/07
Device : Please refer to 2.1.
Revision : A

1.0 Objective:

Qualifying bonding wire material changed from Gold wire to Copper wire for SP1105S-01UTG. Summarize the physical items, electrical characteristics and reliability result of qualification lots.

2.0 Applicable Devices:

2.1 Product name:

Product List
SP1105S-01UTG

3.0 Assembly, Process & Material Differences/Changes:

3.1 Assembly Changes:

No change of assemble process.

3.2 Process Changes:

No change of process method.

3.3 Material Change:

Item	Original	New	Change or not
Lead frame	PPF	PPF	No
Die Attach Material	EN4900GC	EN4900GC	No
Wire	Au 2.0mil*2	PdCu 1.5mil*6	Yes
Mold Compound	G770	G770	No
Plating	PPF	PPF	No

4.0 Packing Method

No change of packing method.

5.0 Physical Differences/Changes:

No change of physical dimension and new pad appearance is same as the one of the original pads.

6.0 Reliability Test Results Summary:

6.1 Reliability summary report:

Test Items	Condition	S/S	Results	ETR #
Pre-conditioning (PC)	JESD22-A113	241 each lot	0/723	TR26-06-024839 TR26-08-025713
DC Blocking (HTRB)	Bias = VRWM, Ta = 150°C, Duration = 1008 Hours	77 each lot	0/231	
Temperature Cycle (TC)	Ta = -55°C to 150°C, Duration = 1000 Cycles	77 each lot	0/231	
Temperature/Humidity (H3TRB)	Ta = 85°C, 85% RH, Bias = VRWM, Duration = 1008 Hours	77 each lot	0/231	
Unbiased HAST (UHAST)	Ta = 130°C, 85%RH, Duration = 96 Hours	77 each lot	0/231	
Resistance to Solder Heat (RSH)	260°C, 10 sec, M-2031	10 each lot	0/30	
Moisture Sensitivity Level (MSL)	Per Jedec J-STD-020D Level 1	241 each lot	0/723	
Solderability (SD)	ANSI-J-STD-002	10 each lot	0/30	

7.0 Electrical Characteristic Summary:

Electrical performances were comparable and characterization data is available upon request.

8.0 Changed Part Identification:

Internal control can identify bonding wire differences.

9.0 Approval:

Sophia Hu
SPA Assistant Product Manager
Littelfuse, Wuxi

Roger Fan
Sr. SPA Product Engineer
Littelfuse, HsinChu

Xin Ye
SPA Product Engineer
Littelfuse, Wuxi